

FOR IMMEDIATE RELEASE

Viasystems Group Joins HDP User Group International

Scottsdale Arizona May 9, 2006. The High Density Packaging User Group International, Inc. (HDP), a global non-profit cooperative research and development organization for the Telecommunications and Computer industries, announced that Viasystems Group, Inc. has joined the organization as a corporate member.

“Viasystems brings a wealth of knowledge and experience to HDP, and their support will be particularly beneficial to our Printed Circuit Board (PCB) and assembly projects.” Said Marshall Andrews, Executive Director of HDP. “All of the companies in HDP welcome Viasystems as our newest member.”

“On behalf of all Viasystems' senior management team and myself, we are extremely excited to participate in the HDP User Group Consortium as a member of Joe Smetana,s Team on the investigation of Via Integrity with Lead-Free soldering.” Stated Kim L. Morton, Materials Engineering Manager of Viasystems. “This is a crucial time for the understanding of many different materials and their respective interactions for Lead-Free Assembly processing. The information learned will be of value to us as well as the PCB Industry as a whole. Thank you very much for this opportunity to be part of this strategic program in these rapidly changing times of Lead-Free.”

About Viasystems.

Viasystems Group, Inc. is a global provider of complex multi-layer printed circuit boards and electro-mechanical components and assemblies. The company's 18,500 employees serve more than 100 customers in the automotive, telecommunications, computer and data communications, industrial and instrumentation and consumer markets.

About the HDP User Group International Inc.

HDP User Group (www.hdpug.org) is a global research and development organization based in Scottsdale AZ, dedicated to “reducing the costs and risks for the Telecommunications and Computer industries when using advanced electronic packaging and assembly”. This international industry led group organizes and conducts R&D programs to address the technical issues facing the industry, including design, printed circuit board manufacturing, electronics assembly, and environmental compliance. HDP maintains additional offices in Austin, Texas; Stockholm, Sweden; and Tokyo, Japan.

For more information, visit HDP User Group on the Internet at www.hdpug.org or contact Darryl Reiner at darrylr@hdpug.org, phone number +1 480-951-1963.

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